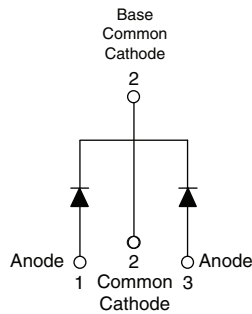


HEXFRED® Ultrafast Soft Recovery Diode, 2 x 4 A


TO-220AB
FEATURES

- Ultrafast recovery
- Ultrasoft recovery
- Very low I_{RRM}
- Very low Q_{rr}
- Specified at operating conditions
- Lead (Pb)-free
- Designed and qualified for industrial level


RoHS*
COMPLIANT

BENEFITS

- Reduced RFI and EMI
- Reduced power loss in diode and switching transistor
- Higher frequency operation
- Reduced snubbing
- Reduced parts count

DESCRIPTION

HFA08TA60C is a state of the art ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 600 V and 4 A per leg continuous current, the HFA08TA60C is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the HEXFRED® product line features extremely low values of peak recovery current (I_{RRM}) and does not exhibit any tendency to “snap-off” during the t_b portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED HFA08TA60C is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

PRODUCT SUMMARY

V_R	600 V
V_F at 4 A at 25 °C	1.8 V
$I_{F(AV)}$	2 x 4 A
t_{rr} (typical)	17 ns
T_J (maximum)	150 °C
Q_{rr}	40 nC
$di_{(rec)M}/dt$	280 A/ μ s

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Cathode to anode voltage	V_R		600	V
Maximum continuous forward current	I_F	$T_C = 100\text{ °C}$	4	A
			8	
Single pulse forward current	I_{FSM}		25	
Maximum repetitive forward current	I_{FRM}		16	
Maximum power dissipation	P_D	$T_C = 25\text{ °C}$	25	W
		$T_C = 100\text{ °C}$	10	
Operating junction and storage temperature range	T_J, T_{Stg}		- 55 to + 150	°C

* Pb containing terminations are not RoHS compliant, exemptions may apply

ELECTRICAL SPECIFICATIONS ($T_J = 25\text{ }^\circ\text{C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Cathode to anode breakdown voltage	V_{BR}	$I_R = 100\text{ }\mu\text{A}$	600	-	-	V
Maximum forward voltage	V_{FM}	$I_F = 4.0\text{ A}$	-	1.5	1.8	
		$I_F = 8.0\text{ A}$	-	1.8	2.2	
		$I_F = 4.0\text{ A}, T_J = 125\text{ }^\circ\text{C}$	-	1.4	1.7	
Maximum reverse leakage current	I_{RM}	$V_R = V_R\text{ rated}$	-	0.17	3.0	μA
		$T_J = 125\text{ }^\circ\text{C}, V_R = 0.8 \times V_R\text{ rated}$	-	44	300	
Junction capacitance	C_T	$V_R = 200\text{ V}$	-	4.0	8.0	pF
Series inductance	L_S	Measured lead to lead 5 mm from package body	-	8.0	-	nH

DYNAMIC RECOVERY CHARACTERISTICS ($T_J = 25\text{ }^\circ\text{C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time See fig. 5, 6 and 16	t_{rr}	$I_F = 1.0\text{ A}, di_F/dt = 200\text{ A}/\mu\text{s}, V_R = 30\text{ V}$	-	17	-	ns
	t_{rr1}	$T_J = 25\text{ }^\circ\text{C}$	-	28	42	
	t_{rr2}	$T_J = 125\text{ }^\circ\text{C}$	-	38	57	
Peak recovery current See fig. 7 and 8	I_{RRM1}	$T_J = 25\text{ }^\circ\text{C}$	-	2.9	5.2	A
	I_{RRM2}	$T_J = 125\text{ }^\circ\text{C}$	-	3.7	6.7	
Reverse recovery charge See fig. 9 and 10	Q_{rr1}	$T_J = 25\text{ }^\circ\text{C}$	-	40	60	nC
	Q_{rr2}	$T_J = 125\text{ }^\circ\text{C}$	-	70	105	
Peak rate of recovery current during t_b See fig. 11 and 12	$di_{(rec)M}/dt1$	$T_J = 25\text{ }^\circ\text{C}$	-	280	-	A/ μs
	$di_{(rec)M}/dt2$	$T_J = 125\text{ }^\circ\text{C}$	-	235	-	

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Lead temperature	T_{lead}	0.063" from case (1.6 mm) for 10 s	-	-	300	$^\circ\text{C}$
Thermal resistance, junction to case	R_{thJC}		-	-	5.0	K/W
Thermal resistance, junction to ambient	R_{thJA}	Typical socket mount	-	-	80	
Thermal resistance, case to heatsink	R_{thCS}	Mounting surface, flat, smooth and greased	-	0.5	-	
Weight			-	2.0	-	g
			-	0.07	-	oz.
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)
Marking device		Case style TO-220AB	HFA08TA60C			

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Vishay High Power Products

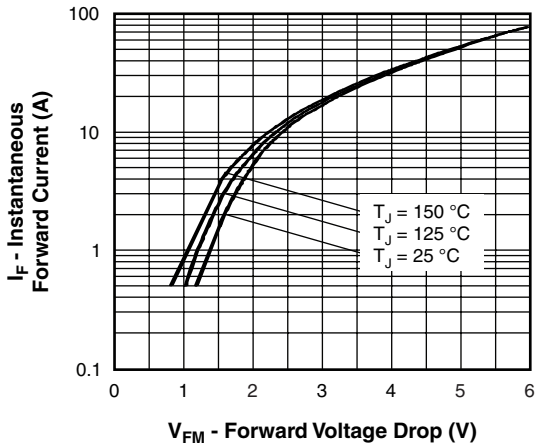


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current

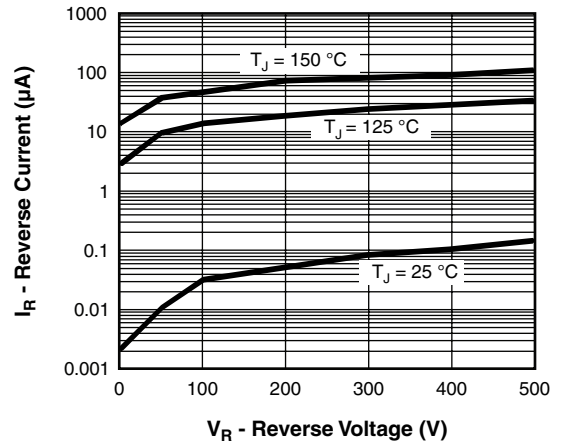


Fig. 2 - Typical Reverse Current vs. Reverse Voltage

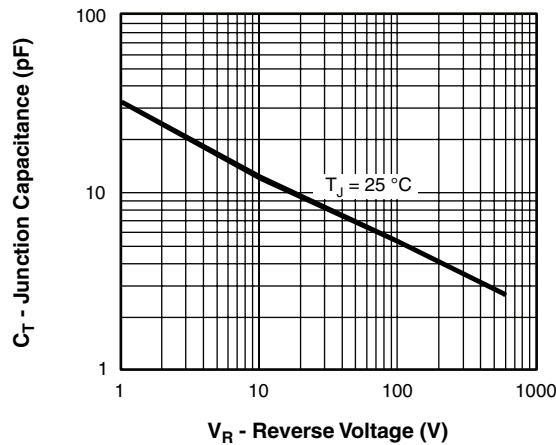


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

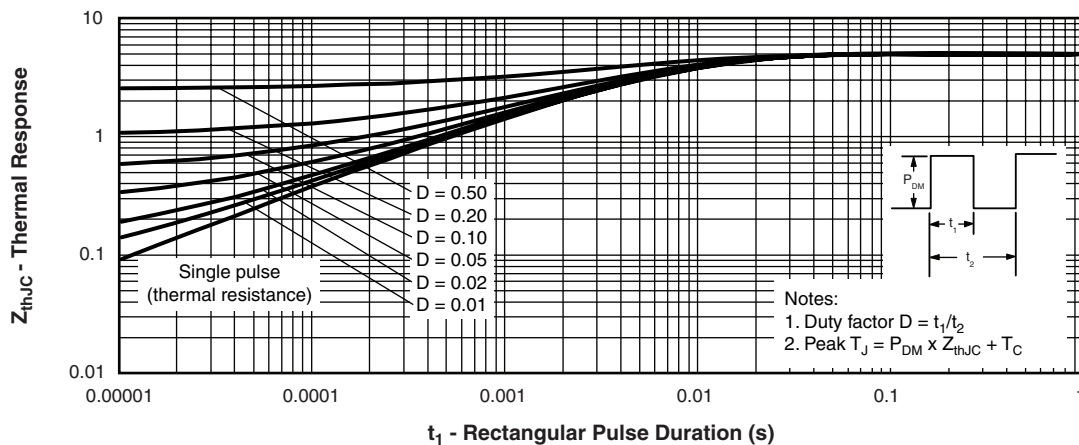


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

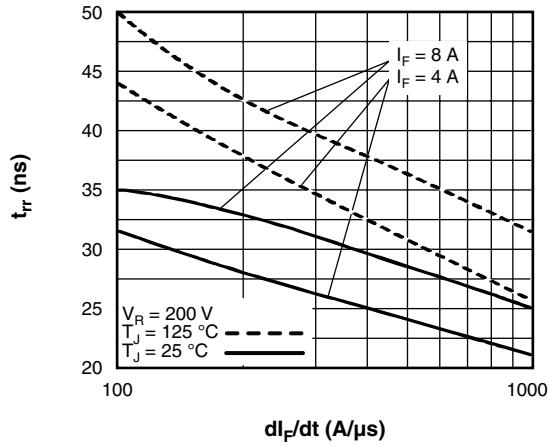


Fig. 5 - Typical Reverse Recovery Time vs. di_F/dt

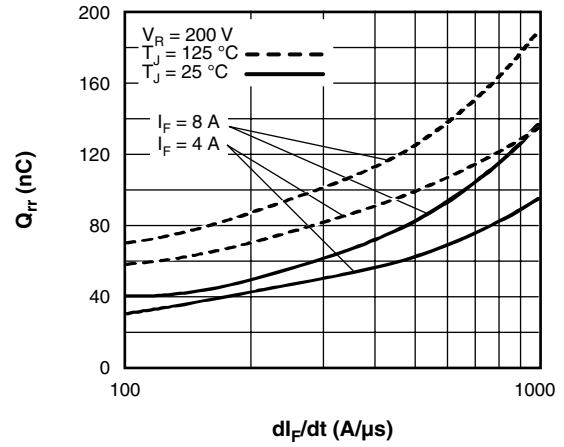


Fig. 7 - Typical Stored Charge vs. di_F/dt

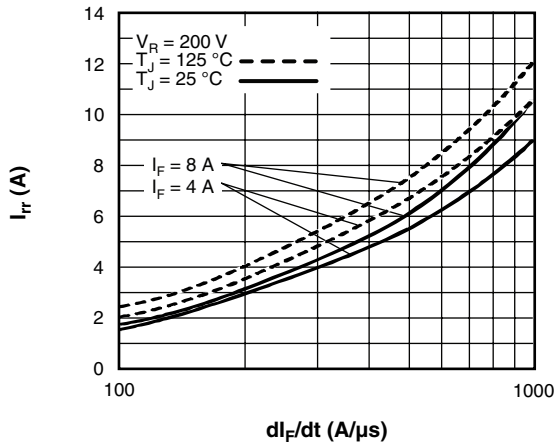


Fig. 6 - Typical Recovery Current vs. di_F/dt

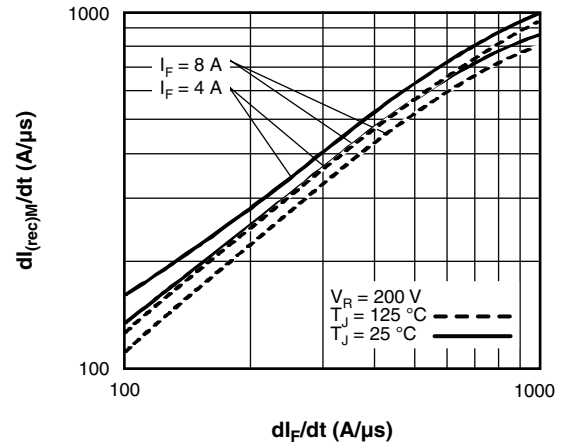


Fig. 8 - Typical $dI_{(rec)M}/dt$ vs. di_F/dt

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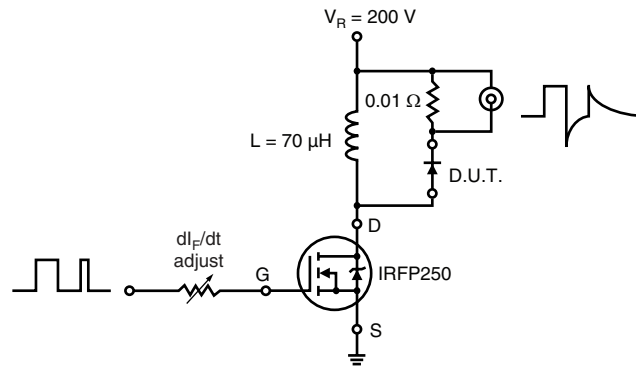
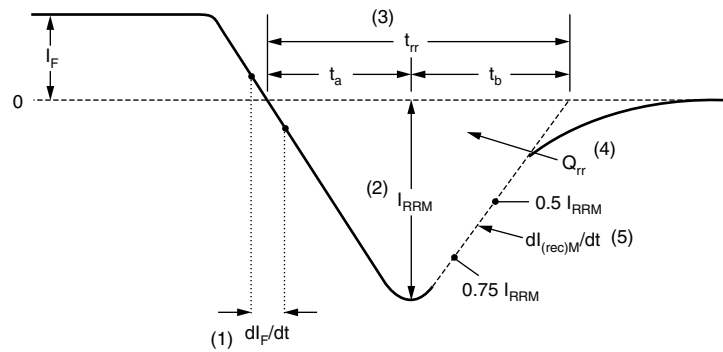


Fig. 9 - Reverse Recovery Parameter Test Circuit



- (1) dI_F/dt - rate of change of current through zero crossing
- (2) I_{RRM} - peak reverse recovery current
- (3) t_{rr} - reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through $0.75 I_{RRM}$ and $0.50 I_{RRM}$ extrapolated to zero current.
- (4) Q_{rr} - area under curve defined by t_{rr} and I_{RRM}
- $$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$
- (5) $dI_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

Fig. 10 - Reverse Recovery Waveform and Definitions

LINKS TO RELATED DOCUMENTS

LINKS TO RELATED DOCUMENTS	
Dimensions	http://www.vishay.com/doc?95222
Part marking information	http://www.vishay.com/doc?95225



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